

PCN Number:	20110913003			PCN Date:	04/09/2013									
Title:	C05 in u*jnr BGA													
Customer Contact:	PCN Manager	Phone:	+1(214)480-6037	Dept:	Quality Services									
Proposed 1st Ship Date:	07/15/2013	Estimated Sample Availability:	04/09/2013											
Change Type:														
<input type="checkbox"/>	Assembly Site	<input checked="" type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Assembly Materials									
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification									
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process									
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process									
<input type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process									
PCN Details														
Description of Change:														
Addition of Copper wire as wire type for C05 devices in u*Jnr package														
Reason for Change:														
Industry wide change of adopting copper wire														
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):														
None														
Changes to product identification resulting from this PCN:														
None														
Product Affected:														
<table border="1"> <tr><td>SN0407067ZQC</td></tr> <tr><td>TVP5150AM1IZQC</td></tr> <tr><td>TVP5150AM1IZQCR</td></tr> <tr><td>TVP5150AM1ZQC</td></tr> <tr><td>TVP5150AM1ZQCR</td></tr> <tr><td>TVP5151IZQC</td></tr> <tr><td>TVP5151IZQCR</td></tr> <tr><td>TVP5151ZQC</td></tr> <tr><td>TVP5151ZQCR</td></tr> </table>						SN0407067ZQC	TVP5150AM1IZQC	TVP5150AM1IZQCR	TVP5150AM1ZQC	TVP5150AM1ZQCR	TVP5151IZQC	TVP5151IZQCR	TVP5151ZQC	TVP5151ZQCR
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TVP5151IZQC														
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TVP5151ZQC														
TVP5151ZQCR														

Qualification Data:

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qualification Schedule: **Start:** **End:** 08/05/2011

Qualification: **Plan** **Test Results**

Qualification Device Construction Details:

	Device 1	Device 2	Device 3
Device:	QIC3106IZQERG6	TVAIC3106IZQER	VSP6825AZRC
Wafer Fab:	DM5	DM5	DM5
Wafer Technology:	1833C05.24LRKD	1833C05.24LRKD	1833C05.24LRKD
Die Size:	3.43599999649528 X 2.68749999725875 mm	2.68699999725926 X 3.43399999649732 mm	2.529586 X 3.057906 mm
Assembly Site:	TAI	PHI	TAI
Package Type/Code:	JRBGA 80 pin	BGA 80 pin	BGA 103 pin
Mold Compound:	CEL-9700HF1	CEL-9700HF1	CEL9700HF10XT
Die Attach:	84-2MVB-TI	84-2MVB-TI	84-2MVB-TI
MSL Rating:	MSL3-260C	MSL3-260C	MSL3-260C
Precon MSL3 (3cy/260C)	900/0	693/0	270/0
Unbiased HAST 130C/85%RH	231/0 96hrs 77/0 192hrs	231/0 1000 cycles 231/0 2000 cycles	-
* Temperature Cycle -55/125C	261/0	231/0 1000 cycles 231/0 2000 cycles	-
* High Temperature Storage Back 150C	231/0 1000hrs 77/0 1500hrs	231/0 1000hrs	-
Moisture Sensitivity, L3	36/0 260C	-	-
Biased HAST, 130C/85%RH	-	-	230/0

Notes:

* Test requires Moisture Preconditioning

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com